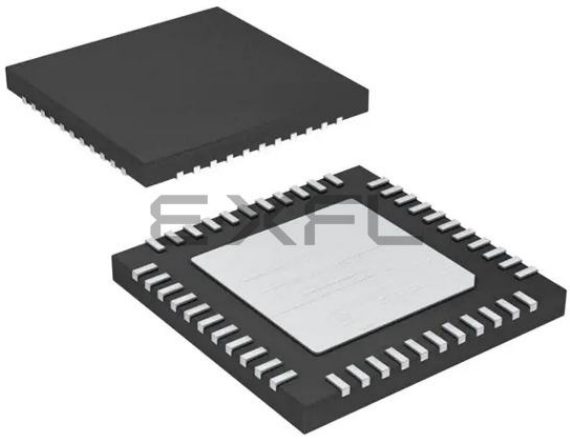

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Peripherals	Brown-out Detect/Reset, LVD, Power Control PWM, QEI, POR, PWM, WDT
Number of I/O	36
Program Memory Size	16KB (8K x 16)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	768 x 8
Voltage - Supply (Vcc/Vdd)	4.2V ~ 5.5V
Data Converters	A/D 9x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
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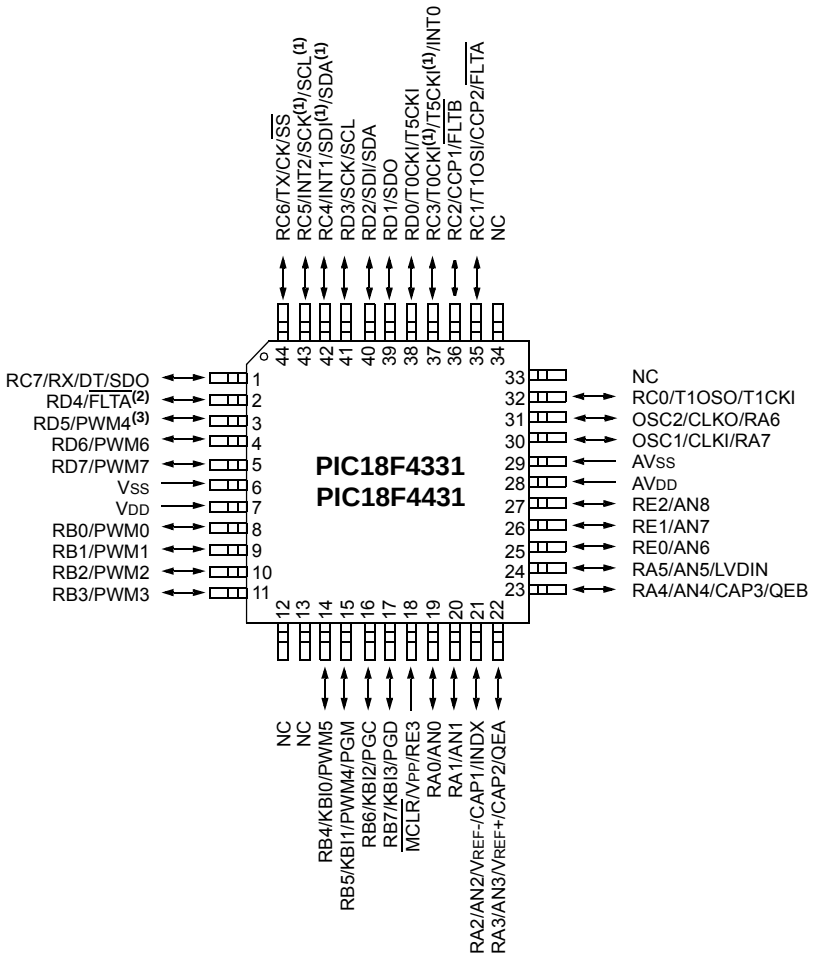
Pin Diagrams (Continued)

44-Pin TQFP



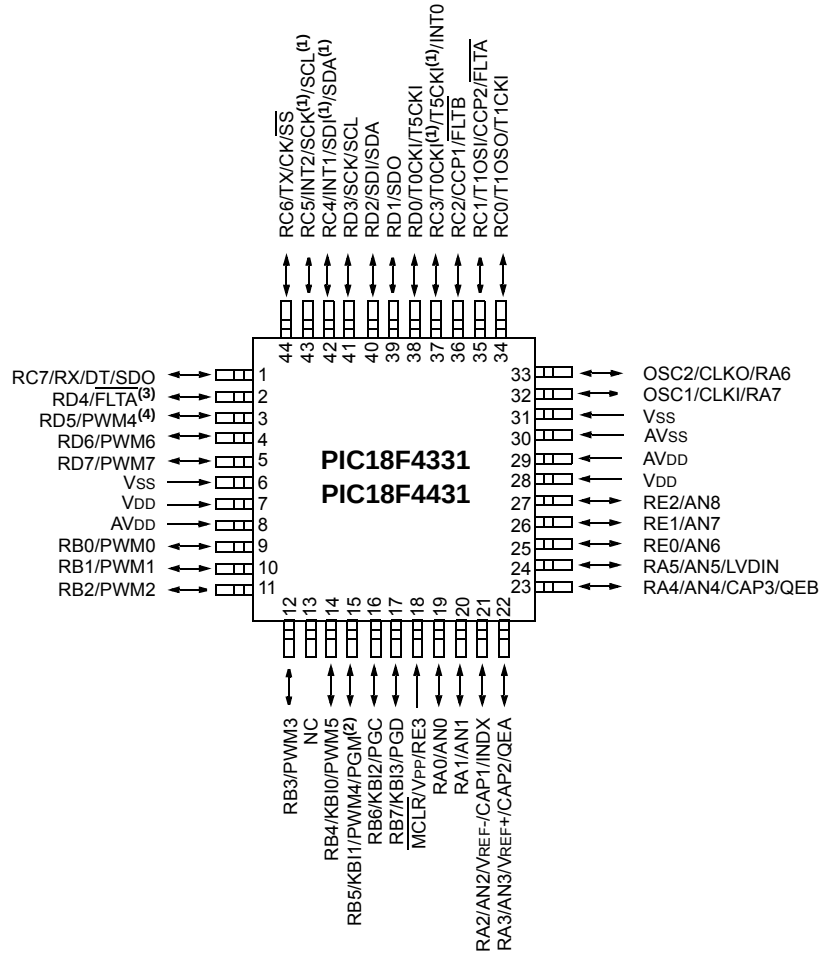
Note 1: RC3 is the alternate pin for T0CKI/T5CKI; RC4 is the alternate pin for SDI/SDA; RC5 is the alternate pin for SCK/SCL.

2: RD4 is the alternate pin for $\overline{\text{FLTA}}$.

3: RD5 is the alternate pin for PWM4.

Pin Diagrams (Continued)

44-Pin QFN(2)



Note 1: RC3 is the alternate pin for T0CKI/T5CKI; RC4 is the alternate pin for SDI/SDA; RC5 is the alternate pin for SCK/SCL.

2: For the QFN package, it is recommended that the bottom pad be connected to VSS.

3: RD4 is the alternate pin for FLTA.

4: RD5 is the alternate pin for PWM4.

4.0 POWER-MANAGED MODES

PIC18F2331/2431/4331/4431 devices offer a total of seven operating modes for more efficient power management. These modes provide a variety of options for selective power conservation in applications where resources may be limited (i.e., battery-powered devices).

There are three categories of power-managed modes:

- Run modes
- Idle modes
- Sleep mode

These categories define which portions of the device are clocked, and sometimes, what speed. The Run and Idle modes may use any of the three available clock sources (primary, secondary or internal oscillator block); the Sleep mode does not use a clock source.

The power-managed modes include several power-saving features offered on previous PIC® devices. One is the clock switching feature, offered in other PIC18 devices, allowing the controller to use the Timer1 oscillator in place of the primary oscillator. Also included is the Sleep mode, offered by all PIC devices, where all device clocks are stopped.

4.1 Selecting Power-Managed Modes

Selecting a power-managed mode requires two decisions: if the CPU is to be clocked or not and the selection of a clock source. The IDLEN bit (OSCCON<7>) controls CPU clocking, while the SCS<1:0> bits (OSCCON<1:0>) select the clock source. The individual modes, bit settings, clock sources and affected modules are summarized in Table 4-1.

4.1.1 CLOCK SOURCES

The SCS<1:0> bits allow the selection of one of three clock sources for power-managed modes. They are:

- the primary clock, as defined by the FOSC<3:0> Configuration bits
- the secondary clock (the Timer1 oscillator)
- the internal oscillator block (for RC modes)

4.1.2 ENTERING POWER-MANAGED MODES

Switching from one power-managed mode to another begins by loading the OSCCON register. The SCS<1:0> bits select the clock source and determine which Run or Idle mode is to be used. Changing these bits causes an immediate switch to the new clock source, assuming that it is running. The switch may also be subject to clock transition delays. These are discussed in **Section 4.1.3 "Clock Transitions and Status Indicators"** and subsequent sections.

Entry to the power-managed Idle or Sleep modes is triggered by the execution of a SLEEP instruction. The actual mode that results depends on the status of the IDLEN bit.

Depending on the current mode and the mode being switched to, a change to a power-managed mode does not always require setting all of these bits. Many transitions may be done by changing the oscillator select bits, or changing the IDLEN bit, prior to issuing a SLEEP instruction. If the IDLEN bit is already configured correctly, it may only be necessary to perform a SLEEP instruction to switch to the desired mode.

TABLE 4-1: POWER-MANAGED MODES

Mode	OSCCON Bits<7,1:0>		Module Clocking		Available Clock and Oscillator Source
	IDLEN(1)	SCS<1:0>	CPU	Peripherals	
Sleep	0	N/A	Off	Off	None – All clocks are disabled
PRI_RUN	N/A	00	Clocked	Clocked	Primary – LP, XT, HS, HSPLL, RC, EC and Internal Oscillator Block.(2) This is the normal, full-power execution mode.
SEC_RUN	N/A	01	Clocked	Clocked	Secondary – Timer1 Oscillator
RC_RUN	N/A	1x	Clocked	Clocked	Internal Oscillator Block(2)
PRI_IDLE	1	00	Off	Clocked	Primary – LP, XT, HS, HSPLL, RC, EC
SEC_IDLE	1	01	Off	Clocked	Secondary – Timer1 Oscillator
RC_IDLE	1	1x	Off	Clocked	Internal Oscillator Block(2)

Note 1: IDLEN reflects its value when the SLEEP instruction is executed.

2: Includes INTOSC and INTOSC postscaler, as well as the INTRC source.

5.0 RESET

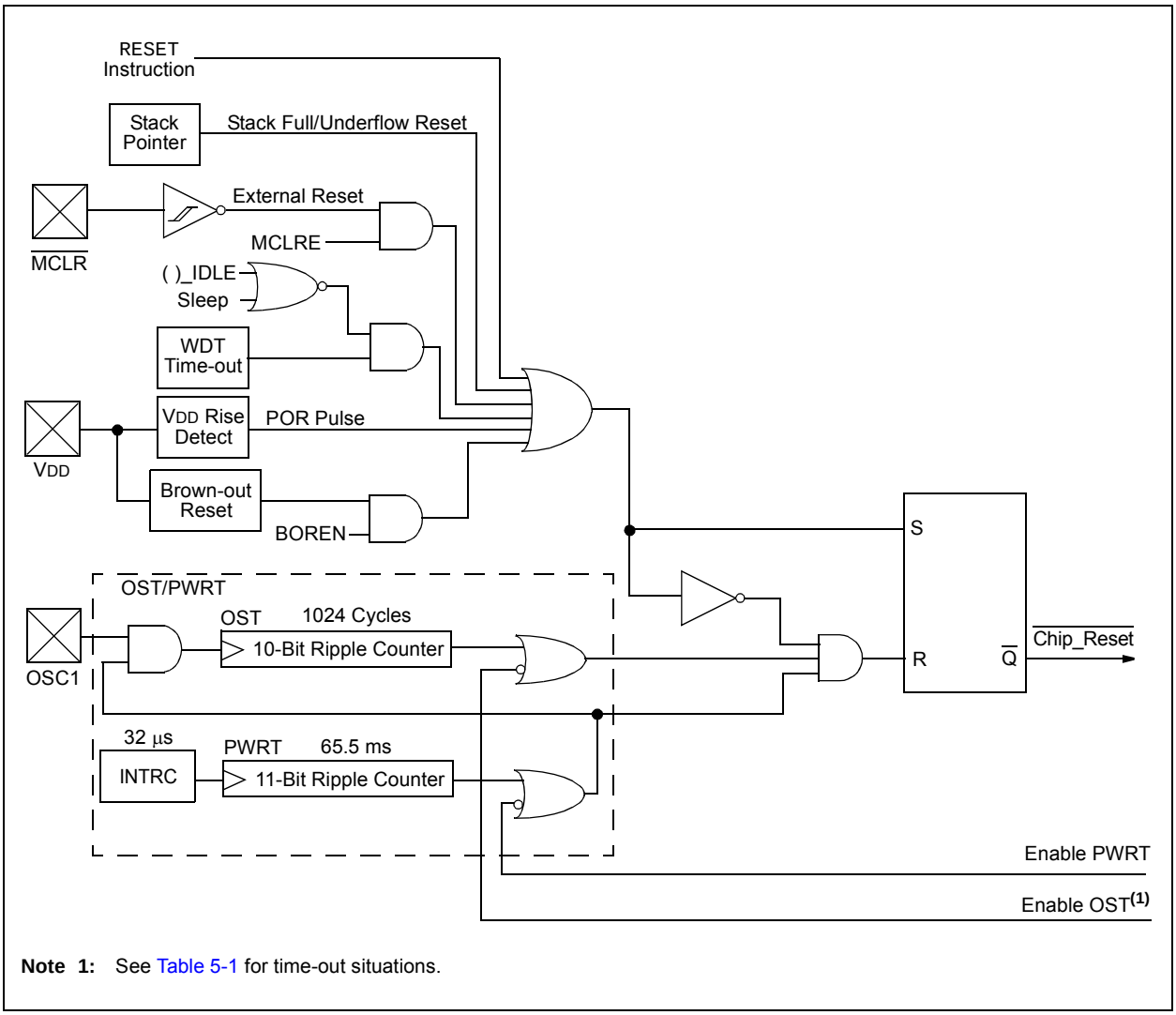
The PIC18F2331/2431/4331/4431 devices differentiate between various kinds of Reset:

a) Power-on Reset (POR)
b) $\overline{\text{MCLR}}$ Reset during normal operation
c) $\overline{\text{MCLR}}$ Reset during Sleep
d) Watchdog Timer (WDT) Reset (during execution)
e) Programmable Brown-out Reset (BOR)
f) RESET Instruction
g) Stack Full Reset
h) Stack Underflow Reset

This section discusses Resets generated by $\overline{\text{MCLR}}$, POR and BOR, and the operation of the various start-up timers. Stack Reset events are covered in **Section 6.1.2.4 "Stack Full/Underflow Resets"**. WDT Resets are covered in **Section 23.2 "Watchdog Timer (WDT)"**.

A simplified block diagram of the On-Chip Reset Circuit is shown in Figure 5-1.

FIGURE 5-1: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT



Note 1: See Table 5-1 for time-out situations.

5.2 Master Clear ($\overline{MCLR}$)

The $\overline{MCLR}$ pin can trigger an external Reset of the device by holding the pin low. These devices have a noise filter in the $\overline{MCLR}$ Reset path that detects and ignores small pulses.

The $\overline{MCLR}$ pin is not driven low by any internal Resets, including the Watchdog Timer.

In PIC18F2331/2431/4331/4431 devices, the $\overline{MCLR}$ input can be disabled with the MCLRE Configuration bit. When $\overline{MCLR}$ is disabled, the pin becomes a digital input. For more information, see **Section 11.5 "PORTE, TRISE and LATE Registers"**.

5.3 Power-on Reset (POR)

A Power-on Reset pulse is generated on-chip whenever VDD rises above a certain threshold. This allows the device to start in the initialized state when VDD is adequate for operation.

To take advantage of the POR circuitry, tie the $\overline{MCLR}$ pin through a resistor (1 kΩ to 10 kΩ) to VDD. This will eliminate external RC components usually needed to create a Power-on Reset delay. The minimum rise rate for VDD is specified (Parameter D004). For a slow rise time, see Figure 5-2.

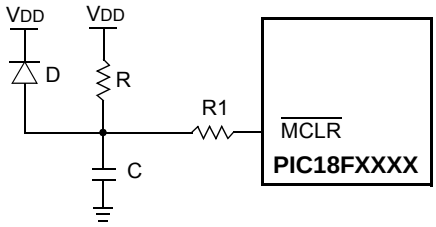
When the device starts normal operation (i.e., exits the Reset condition), device operating parameters (such as voltage, frequency and temperature) must be met to ensure operation. If these conditions are not met, the device must be held in Reset until the operating conditions are met.

Power-on Reset events are captured by the $\overline{POR}$ bit (RCON<1>). The state of the bit is set to '0' whenever a POR occurs and does not change for any other Reset event. $\overline{POR}$ is not reset to '1' by any hardware event. To capture multiple events, the user manually resets the bit to '1' in software following any Power-on Reset.

Note: The following decoupling method is recommended:

1. A 1 µF capacitor should be connected across AVDD and AVSS.
2. A similar capacitor should be connected across VDD and VSS.

FIGURE 5-2: EXTERNAL POWER-ON RESET CIRCUIT (FOR SLOW VDD POWER-UP)



Note 1: External Power-on Reset circuit is required only if the VDD power-up slope is too slow. The diode, D, helps discharge the capacitor quickly when VDD powers down.

2: R < 40 kΩ is recommended to make sure that the voltage drop across R does not violate the device's electrical specification.

3: R1 ≥ 1 kΩ will limit any current flowing into $\overline{MCLR}$ from external capacitor, C, in the event of $\overline{MCLR}$/VPP pin breakdown, due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS).

5.4 Brown-out Reset (BOR)

A Configuration bit, BOREN, can disable (if clear/programmed) or enable (if set) the Brown-out Reset circuitry. If VDD falls below VBOR (Parameter D005A through D005F) for greater than TBOR (Parameter 35), the brown-out situation will reset the chip. A Reset may not occur if VDD falls below VBOR for less than TBOR. The chip will remain in Brown-out Reset until VDD rises above VBOR. If the Power-up Timer is enabled, it will be invoked after VDD rises above VBOR; it then will keep the chip in Reset for an additional time delay TPWRT (Parameter 33). If VDD drops below VBOR while the Power-up Timer is running, the chip will go back into a Brown-out Reset and the Power-up Timer will be initialized. Once VDD rises above VBOR, the Power-up Timer will execute the additional time delay. Enabling the Brown-out Reset does not automatically enable the PWRT.

TABLE 5-3: INITIALIZATION CONDITIONS FOR ALL REGISTERS (CONTINUED)

Register	Applicable Devices				Power-on Reset, Brown-out Reset	$\overline{\text{MCLR}}$ Resets WDT Reset RESET Instruction Stack Resets	Wake-up via WDT or Interrupt
ADRESH	2331	2431	4331	4431	xxxx xxxx	uuuu uuuu	uuuu uuuu
ADRESL	2331	2431	4331	4431	xxxx xxxx	uuuu uuuu	uuuu uuuu
ADCON0	2331	2431	4331	4431	--00 0000	--00 0000	--uu uuuu
ADCON1	2331	2431	4331	4431	00-0 0000	00-0 0000	uu-u uuuu
ADCON2	2331	2431	4331	4431	0000 0000	0000 0000	uuuu uuuu
ADCON3	2331	2431	4331	4431	00-0 0000	00-0 0000	uu-u uuuu
ADCHS	2331	2431	4331	4431	0000 0000	0000 0000	uuuu uuuu
CCPR1H	2331	2431	4331	4431	xxxx xxxx	uuuu uuuu	uuuu uuuu
CCPR1L	2331	2431	4331	4431	xxxx xxxx	uuuu uuuu	uuuu uuuu
CCP1CON	2331	2431	4331	4431	--00 0000	--00 0000	--uu uuuu
CCPR2H	2331	2431	4331	4431	xxxx xxxx	uuuu uuuu	uuuu uuuu
CCPR2L	2331	2431	4331	4431	xxxx xxxx	uuuu uuuu	uuuu uuuu
CCP2CON	2331	2431	4331	4431	--00 0000	--00 0000	--uu uuuu
ANSEL1	2331	2431	4331	4431	---- ---1	---- ---1	---- ---u
ANSEL0	2331	2431	4331	4431	1111 1111	1111 1111	uuuu uuuu
T5CON	2331	2431	4331	4431	0000 0000	0000 0000	uuuu uuuu
QEICON	2331	2431	4331	4431	0000 0000	0000 0000	uuuu uuuu
SPBRGH	2331	2431	4331	4431	0000 0000	0000 0000	uuuu uuuu
SPBRG	2331	2431	4331	4431	0000 0000	0000 0000	uuuu uuuu
RCREG	2331	2431	4331	4431	0000 0000	0000 0000	uuuu uuuu
TXREG	2331	2431	4331	4431	0000 0000	0000 0000	uuuu uuuu
TXSTA	2331	2431	4331	4431	0000 -010	0000 -010	uuuu -uuu
RCSTA	2331	2431	4331	4431	0000 000x	0000 000x	uuuu uuuu
BAUDCON	2331	2431	4331	4431	-1-1 0-00	-1-1 0-00	-u-u u-uu
EEADR	2331	2431	4331	4431	0000 0000	0000 0000	uuuu uuuu
EEDATA	2331	2431	4331	4431	0000 0000	0000 0000	uuuu uuuu
EECON2	2331	2431	4331	4431	0000 0000	0000 0000	0000 0000
EECON1	2331	2431	4331	4431	xx-0 x000	uu-0 u000	uu-0 u000
IPR3	2331	2431	4331	4431	---1 1111	---1 1111	---u uuuu
PIE3	2331	2431	4331	4431	---0 0000	---0 0000	---u uuuu
PIR3	2331	2431	4331	4431	---0 0000	---0 0000	---u uuuu

Legend: u = unchanged, x = unknown, - = unimplemented bit, read as '0', q = value depends on condition. Shaded cells indicate conditions do not apply for the designated device.

Note 1: One or more bits in the INTCONx or PIRx registers will be affected (to cause wake-up).

2: When the wake-up is due to an interrupt and the GIEL or GIEH bit is set, the PC is loaded with the interrupt vector (0008h or 0018h).

3: When the wake-up is due to an interrupt and the GIEL or GIEH bit is set, the TOSU, TOSH and TOSL are updated with the current value of the PC. The STKPTR is modified to point to the next location in the hardware stack.

4: See Table 5-2 for Reset value for specific condition.

5: Bits 6 and 7 of PORTA, LATA and TRISA are enabled depending on the oscillator mode selected. When not enabled as PORTA pins, they are disabled and read '0'.

6: Bit 3 of PORTE and LATE are enabled if $\overline{\text{MCLR}}$ functionality is disabled. When not enabled as the PORTE pin, they are disabled and read as '0'. The 28-pin devices do not have only RE3 implemented.

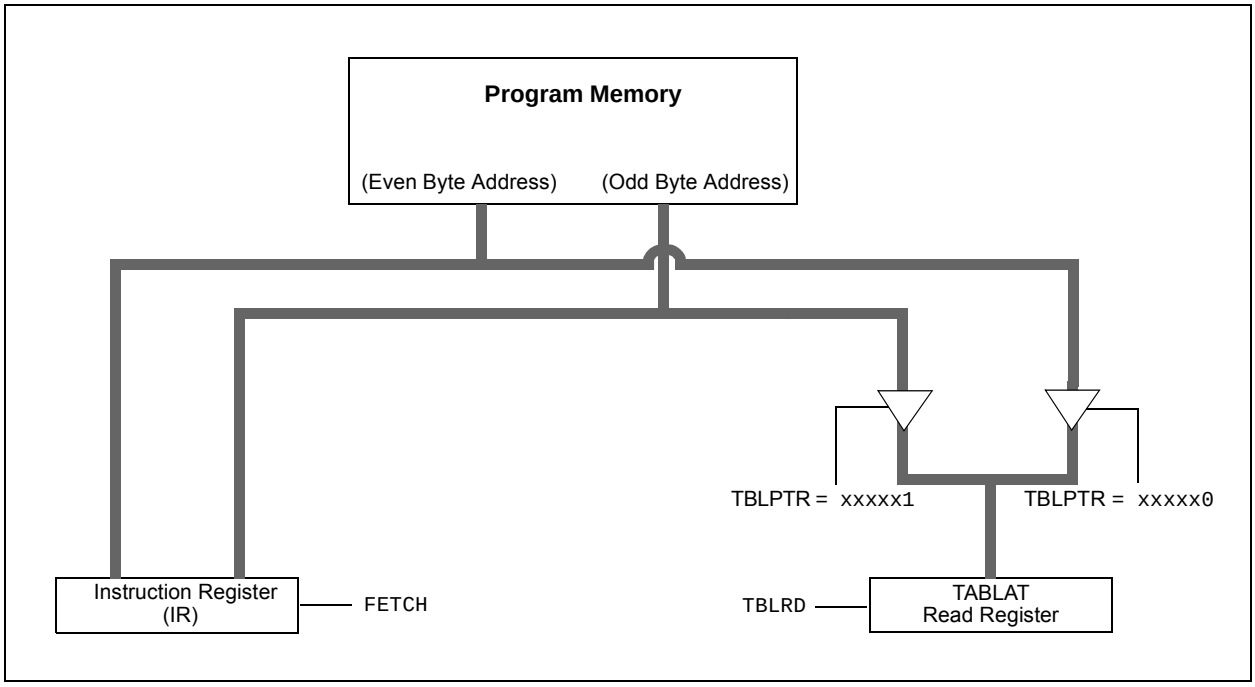
8.3 Reading the Flash Program Memory

The TBLRD instruction is used to retrieve data from program memory and place it into data RAM. Table reads from program memory are performed one byte at a time.

TBLPTR points to a byte address in program space. Executing a TBLRD instruction places the byte pointed to into TABLAT. In addition, TBLPTR can be modified automatically for the next table read operation.

The internal program memory is typically organized by words. The Least Significant bit of the address selects between the high and low bytes of the word. Figure 8-4 shows the interface between the internal program memory and the TABLAT.

FIGURE 8-4: READS FROM FLASH PROGRAM MEMORY



EXAMPLE 8-1: READING A FLASH PROGRAM MEMORY WORD

```
            MOVLW   CODE_ADDR_UPPER             ; Load TBLPTR with the base
            MOVWF   TBLPTRU                     ; address of the word
            MOVLW   CODE_ADDR_HIGH
            MOVWF   TBLPTRH
            MOVLW   CODE_ADDR_LOW
            MOVWF   TBLPTRL
READ_WORD
            TBLRD*+                             ; read into TABLAT and increment TBLPTR
            MOVF    TABLAT,W                    ; get data
            MOVWF   WORD_EVEN
            TBLRD*+                             ; read into TABLAT and increment TBLPTR
            MOVF    TABLAT,W                    ; get data
            MOVWF   WORD_ODD
```

REGISTER 10-9: PIE3: PERIPHERAL INTERRUPT ENABLE REGISTER 3

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	PTIE	IC3DRIE	IC2QEIE	IC1IE	TMR5IE
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-5 **Unimplemented:** Read as '0'

bit 4 **PTIE:** PWM Time Base Interrupt Enable bit
1 = PTIF enabled
0 = PTIF disabled

bit 3 **IC3DRIE:** IC3 Interrupt Enable/Direction Change Interrupt Enable bit
IC3 Enabled (CAP3CON<3:0>):
1 = IC3 interrupt enabled
0 = IC3 interrupt disabled
QEI Enabled (QEIM<2:0>):
1 = Change of direction interrupt enabled
0 = Change of direction interrupt disabled

bit 2 **IC2QEIE:** IC2 Interrupt Flag/QEI Interrupt Flag Enable bit
IC2 Enabled (CAP2CON<3:0>):
1 = IC2 interrupt enabled)
0 = IC2 interrupt disabled
QEI Enabled (QEIM<2:0>):
1 = QEI interrupt enabled
0 = QEI interrupt disabled

bit 1 **IC1IE:** IC1 Interrupt Enable bit
1 = IC1 interrupt enabled
0 = IC1 interrupt disabled

bit 0 **TMR5IE:** Timer5 Interrupt Enable bit
1 = Timer5 interrupt enabled
0 = Timer5 interrupt disabled

17.1.5 ENTERING INPUT CAPTURE MODE AND CAPTURE TIMING

The following is a summary of functional operation upon entering any of the Input Capture modes:

1. After the module is configured for one of the Capture modes by setting the Capture Mode Select bits (CAPxM<3:0>), the first detected edge captures the Timer5 value and stores it in the CAPxBUF register. The timer is then reset (depending on the setting of CAPxREN bit) and starts to increment according to its settings (see Figure 17-4, Figure 17-5 and Figure 17-6).
2. On all edges, the capture logic performs the following:
   a) Input Capture mode is decoded and the active edge is identified.
   b) The CAPxREN bit is checked to determine whether Timer5 is reset or not.
   c) On every active edge, the Timer5 value is recorded in the Input Capture Buffer (CAPxBUF).
   d) Reset Timer5 after capturing the value of the timer when the CAPxREN bit is enabled. Timer5 is reset on every active capture edge in this case.
   e) On all continuing capture edge events, repeat steps (a) through (d) until the operational mode is terminated, either by user firmware, POR or BOR.
   f) The timer value is not affected when switching into and out of various Input Capture modes.

17.1.6 TIMER5 RESET

Every input capture trigger can optionally reset (TMR5). The Capture Reset Enable bit, CAPxREN, gates the automatic Reset of the time base of the capture event with this enable Reset signal. All capture events reset the selected timer when CAPxREN is set. Resets are disabled when CAPxREN is cleared (see Figure 17-4, Figure 17-5 and Figure 17-6).

Note:	The CAPxREN bit has no effect in Pulse-Width Measurement mode.

17.1.7 IC INTERRUPTS

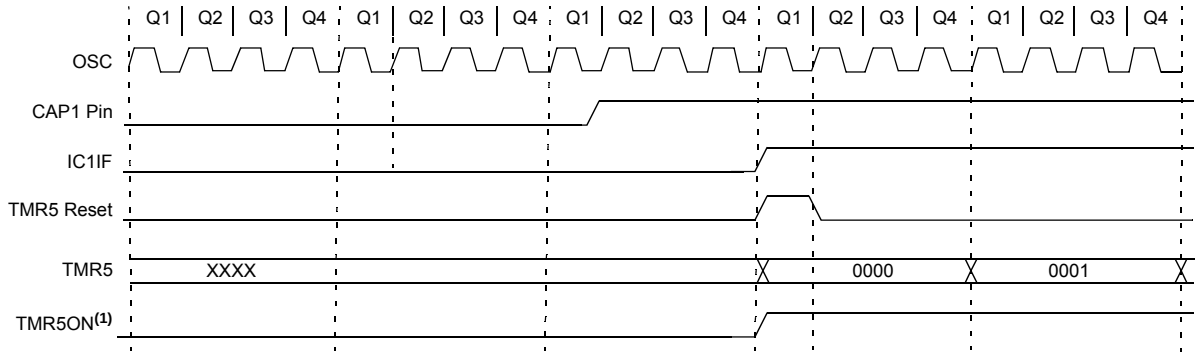
There are four operating modes for which the IC module can generate an interrupt and set one of the Interrupt Capture Flag bits (IC1IF, IC2QEIF or IC3DRIF). The interrupt flag that is set depends on the channel in which the event occurs. The modes are:

- Edge Capture (CAPxM<3:0> = 0001, 0010, 0011 or 0100)
- Period Measurement Event (CAPxM<3:0> = 0101)
- Pulse-Width Measurement Event (CAPxM<3:0> = 0110 or 0111)
- State Change Event (CAPxM<3:0> = 1000)

Note:	The Special Event Trigger is generated only in the Special Event Trigger mode on the CAP1 input (CAP1M<3:0> = 1110 and 1111). IC1IF interrupt is not set in this mode.

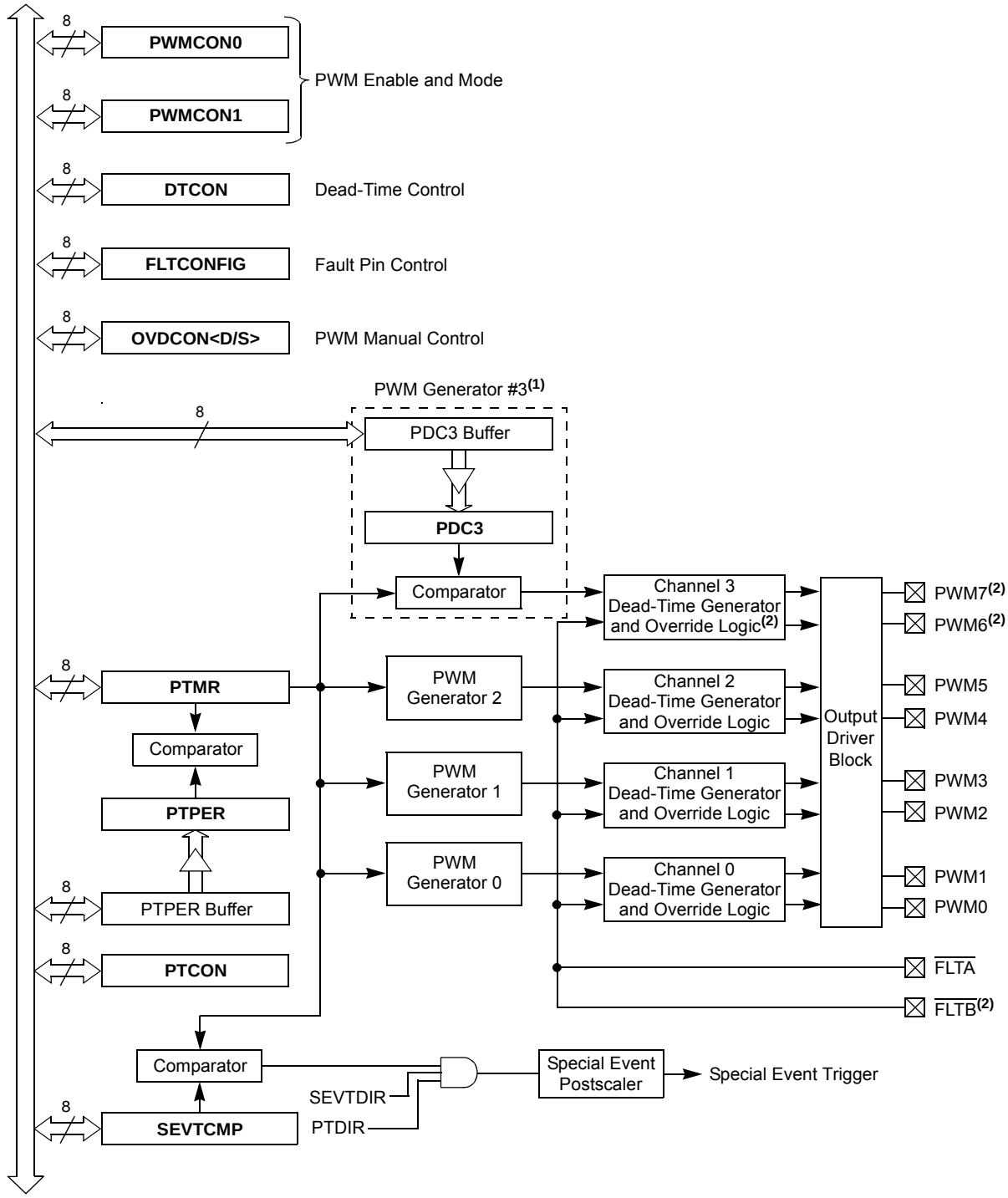
The timing of interrupt and Special Event Trigger events is shown in Figure 17-7. Any active edge is detected on the rising edge of Q2 and propagated on the rising edge of Q4 rising edge. If an active edge happens to occur any later than this (on the falling edge of Q2, for example), then it will be recognized on the next Q2 rising edge.

FIGURE 17-7: CAPx INTERRUPTS AND IC1 SPECIAL EVENT TRIGGER



Note 1: Timer5 is only reset and enabled (assuming TMR5ON = 0 and T5MOD = 1) when the Special Event Trigger Reset is enabled for the Timer5 Reset input. The TMR5ON bit is asserted and Timer5 is reset on the Q1 rising edge following the event capture. With the Special Event Trigger Reset disabled, Timer5 cannot be reset by the Special Event Trigger Reset on the CAP1 input. In order for the Special Event Trigger Reset to work as the Reset trigger to Timer5, IC1 must be configured in the Special Event Trigger mode (CAP1M<3:0> = 1110 or 1111).

FIGURE 18-1: POWER CONTROL PWM MODULE BLOCK DIAGRAM



Note 1: Only PWM Generator 3 is shown in detail. The other generators are identical; their details are omitted for clarity.

2: PWM Generator 3 and its logic, PWM Channels 6 and 7, and $\overline{FLTB}$ and its associated logic are not implemented on PIC18F2331/2431 devices.

19.3.1.1 Addressing

Once the SSP module has been enabled, it waits for a Start condition to occur. Following the Start condition, the 8 bits are shifted into the SSPSR register. All incoming bits are sampled with the rising edge of the clock (SCL) line. The value of register SSPSR<7:1> is compared to the value of the SSPADD register. The address is compared on the falling edge of the eighth clock (SCL) pulse. If the addresses match, and the BF and SSPOV bits are clear, the following events occur:

a) The SSPSR register value is loaded into the SSPBUF register.
b) The Buffer Full bit, BF, is set.
c) An $\overline{\text{ACK}}$ pulse is generated.
d) SSP Interrupt Flag bit, SSPIF (PIR1<3>), is set (interrupt is generated if enabled) on the falling edge of the ninth SCL pulse.

In 10-Bit Addressing mode, two address bytes need to be received by the slave (Figure 19-7). The five Most Significant bits (MSbs) of the first address byte specify if this is a 10-bit address. Bit R/$\overline{\text{W}}$ (SSPSTAT<2>) must specify a write so the slave device will receive the second address byte. For a 10-bit address, the first byte would equal '1111 0 A9 A8 0', where A9 and A8 are the two MSbs of the address.

The sequence of events for 10-Bit Addressing mode is as follows, with Steps 7-9 for slave-transmitter:

1. Receive first (high) byte of address (SSPIF, BF and UA bits are set).
2. Update the SSPADD register with second (low) byte of address (clears bit, UA, and releases the SCL line).
3. Read the SSPBUF register (clears bit, BF) and clear flag bit, SSPIF.
4. Receive second (low) byte of address (SSPIF, BF and UA bits are set).
5. Update the SSPADD register with the first (high) byte of address. If match releases SCL line, this will clear bit, UA.
6. Read the SSPBUF register (clears bit, BF) and clear flag bit, SSPIF.
7. Receive Repeated Start condition.
8. Receive first (high) byte of address (SSPIF and BF bits are set).
9. Read the SSPBUF register (clears bit, BF) and clear flag bit, SSPIF.

TABLE 19-2: DATA TRANSFER RECEIVED BYTE ACTIONS

Status Bits as Data Transfer is Received		SSPSR → SSPBUF	Generate $\overline{\text{ACK}}$ Pulse	Set SSPIF Bit (SSP interrupt occurs if enabled)
BF	SSPOV			
0	0	Yes	Yes	Yes
1	0	No	No	Yes
1	1	No	No	Yes
0	1	No	No	Yes

Note: Shaded cells show the conditions where the user software did not properly clear the overflow condition.

TABLE 20-3: BAUD RATES FOR ASYNCHRONOUS MODES (CONTINUED)

BAUD RATE (K)	SYNC = 0, BRGH = 1, BRG16 = 1 or SYNC = 1, BRG16 = 1											
	FOSC = 40.000 MHz			FOSC = 20.000 MHz			FOSC = 10.000 MHz			FOSC = 8.000 MHz		
	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)
0.3	0.300	0.00	33332	0.300	0.00	16665	0.300	0.00	8332	0.300	-0.01	6665
1.2	1.200	0.00	8332	1.200	0.02	4165	1.200	0.02	2082	1.200	-0.04	1665
2.4	2.400	0.02	4165	2.400	0.02	2082	2.402	0.06	1040	2.400	-0.04	832
9.6	9.606	0.06	1040	9.596	-0.03	520	9.615	0.16	259	9.615	-0.16	207
19.2	19.193	-0.03	520	19.231	0.16	259	19.231	0.16	129	19.230	-0.16	103
57.6	57.803	0.35	172	57.471	-0.22	86	58.140	0.94	42	57.142	0.79	34
115.2	114.943	-0.22	86	116.279	0.94	42	113.636	-1.36	21	117.647	-2.12	16

BAUD RATE (K)	SYNC = 0, BRGH = 1, BRG16 = 1 or SYNC = 1, BRG16 = 1								
	FOSC = 4.000 MHz			FOSC = 2.000 MHz			FOSC = 1.000 MHz		
	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)	Actual Rate (K)	% Error	SPBRG value (decimal)
0.3	0.300	0.01	3332	0.300	-0.04	1665	0.300	-0.04	832
1.2	1.200	0.04	832	1.201	-0.16	415	1.201	-0.16	207
2.4	2.404	0.16	415	2.403	-0.16	207	2.403	-0.16	103
9.6	9.615	0.16	103	9.615	-0.16	51	9.615	-0.16	25
19.2	19.231	0.16	51	19.230	-0.16	25	19.230	-0.16	12
57.6	58.824	2.12	16	55.555	3.55	8	—	—	—
115.2	111.111	-3.55	8	—	—	—	—	—	—

REGISTER 21-1: ADCON0: A/D CONTROL REGISTER 0

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	ACONV	ACSCH	ACMOD1	ACMOD0	GO/$\overline{\text{DONE}}$	ADON
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-6 **Unimplemented:** Read as '0'

bit 5 **ACONV**: Auto-Conversion Continuous Loop or Single-Shot Mode Select bit
1 = Continuous Loop mode enabled
0 = Single-Shot mode enabled

bit 4 **ACSCH**: Auto-Conversion Single or Multi-Channel Mode bit
1 = Multi-Channel mode enabled, Single Channel mode disabled
0 = Single Channel mode enabled, Multi-Channel mode disabled

bit 3-2 **ACMOD<1:0>:** Auto-Conversion Mode Sequence Select bits

If ACSCH = 1:
00 = Sequential Mode 1 (SEQM1); two samples are taken in sequence:
1st sample: Group A(1)
2nd sample: Group B(1)
01 = Sequential Mode 2 (SEQM2); four samples are taken in sequence:
1st sample: Group A(1)
2nd sample: Group B(1)
3rd sample: Group C(1)
4th sample: Group D(1)
10 = Simultaneous Mode 1 (STNM1); two samples are taken simultaneously:
1st sample: Group A and Group B(1)
11 = Simultaneous Mode 2 (STNM2); two samples are taken simultaneously:
1st sample: Group A and Group B(1)
2nd sample: Group C and Group D(1)

If ACSCH = 0, Auto-Conversion Single Channel Sequence Mode Enabled:
00 = Single Channel Mode 1 (SCM1); Group A is taken and converted(1)
01 = Single Channel Mode 2 (SCM2); Group B is taken and converted(1)
10 = Single Channel Mode 3 (SCM3); Group C is taken and converted(1)
11 = Single Channel Mode 4 (SCM4); Group D is taken and converted(1)

bit 1 **GO/$\overline{\text{DONE}}$**: A/D Conversion Status bit
1 = A/D conversion cycle in progress. Setting this bit starts the A/D conversion cycle. If Auto-Conversion Single-Shot mode is enabled (ACONV = 0), this bit is automatically cleared by hardware when the A/D conversion (single or multi-channel depending on ACMOD settings) has completed. If Auto-Conversion Continuous Loop mode is enabled (ACONV = 1), this bit remains set after the user/trigger has set it (continuous conversions). It may be cleared manually by the user to stop the conversions.
0 = A/D conversion or multiple conversions completed/not in progress

bit 0 **ADON:** A/D On bit
1 = A/D Converter module is enabled (after brief power-up delay, starts continuous sampling)
0 = A/D Converter module is disabled

Note 1: Groups A, B, C, and D refer to the ADCHS register.

REGISTER 21-2: ADCON1: A/D CONTROL REGISTER 1

R/W-0	R/W-0	U-0	R/W-0	R-0	R-0	R-0	R-0
VCFG1	VCFG0	—	FIFOEN	BFEMT	BFOVL	ADPNT1	ADPNT0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-6 **VCFG<1:0>:** A/D VREF+ and A/D VREF- Source Selection bits
00 = VREF+ = AVDD, VREF- = AVSS (AN2 and AN3 are analog inputs or digital I/O)
01 = VREF+ = External VREF+, VREF- = AVSS (AN2 is an analog input or digital I/O)
10 = VREF+ = AVDD, VREF- = External VREF- (AN3 is an analog input or digital I/O)
11 = VREF+ = External VREF-, VREF- = External VREF-

bit 5 **Unimplemented:** Read as '0'

bit 4 **FIFOEN**: FIFO Buffer Enable bit
1 = FIFO is enabled
0 = FIFO is disabled

bit 3 **BFEMT**: Buffer Empty bit
1 = FIFO is empty
0 = FIFO is not empty (at least one of four locations has unread A/D result data)

bit 2 **BFOVFL**: Buffer Overflow bit
1 = A/D result has overwritten a buffer location that has unread data
0 = A/D result has not overflowed

bit 1-0 **ADPNT<1:0>**: Buffer Read Pointer Location bits
Designates the location to be read next.
00 = Buffer Address 0
01 = Buffer Address 1
10 = Buffer Address 2
11 = Buffer Address 3

21.1.3 CONVERSION SEQUENCING

The ACMOD<1:0> bits control the sequencing of the A/D conversions. When ACSCH = 0, the A/D is configured to sample and convert a single channel. The ACMOD bits select which group to perform the conversions and the GxSEL<1:0> bits select which channel in the group is to be converted. If Single-Shot mode is enabled, the A/D interrupt flag will be set after the channel is converted. If Continuous Loop mode is enabled, the A/D interrupt flag will be set according to the ADRS<1:0> bits.

When ACSCH = 1, multiple channel sequencing is enabled and two submodes can be selected. The first mode is Sequential mode with two settings. The first setting is called SEQM1, and first samples and converts the selected Group A channel, and then samples and converts the selected Group B channel. The second mode is called SEQM2, and it samples and converts a Group A channel, Group B channel, Group C channel and finally, a Group D channel.

The second multiple channel sequencing submode is Simultaneous Sampling mode. In this mode, there are also two settings. The first setting is called STNM1, and uses the two sample and hold circuits on the A/D module. The selected Group A and B channels are simultaneously sampled and then the Group A channel is converted followed by the conversion of the Group B channel. The second setting is called STNM2, and starts the same as STNM1, but follows it with a simultaneous sample of Group C and D channels. The A/D module will then convert the Group C channel followed by the Group D channel.

21.1.4 TRIGGERING A/D CONVERSIONS

The PIC18F2331/2431/4331/4431 devices are capable of triggering conversions from many different sources. The same method used by all other microcontrollers of setting the GO/$\overline{\text{DONE}}$ bit still works. The other trigger sources are:

- RC3/INT0 Pin
- Timer5 Overflow
- Input Capture 1 (IC1)
- CCP2 Compare Match
- Power Control PWM Rising Edge

These triggers are enabled using the SSRC<4:0> bits (ADCON3<4:0>). Any combination of the five sources can trigger a conversion by simply setting the corresponding bit in ADCON3. When the trigger occurs, the GO/$\overline{\text{DONE}}$ bit is automatically set by the hardware and then cleared once the conversion completes.

21.1.5 A/D MODULE INITIALIZATION STEPS

The following steps should be followed to initialize the A/D module:

1. Configure the A/D module:
   a) Configure the analog pins, voltage reference and digital I/O.
   b) Select the A/D input channels.
   c) Select the A/D Auto-Conversion mode (Single-Shot or Continuous Loop).
   d) Select the A/D conversion clock.
   e) Select the A/D conversion trigger.
2. Configure the A/D interrupt (if required):
   a) Set the GIE bit.
   b) Set the PEIE bit.
   c) Set the ADIE bit.
   d) Clear the ADIF bit.
   e) Select the A/D trigger setting.
   f) Select the A/D interrupt priority.
3. Turn on ADC:
   a) Set the ADON bit in the ADCON0 register.
   b) Wait the required power-up setup time, about 5-10 μs.
4. Start the sample/conversion sequence:
   a) Sample for a minimum of 2 T_{AD} and start the conversion by setting the GO/$\overline{\text{DONE}}$ bit. The GO/$\overline{\text{DONE}}$ bit is set by the user in software or by the module if initiated by a trigger.
   b) If T_{ACQ} is assigned a value (multiple of T_{AD}), then setting the GO/$\overline{\text{DONE}}$ bit starts a sample period of the T_{ACQ} value, then starts a conversion.
5. Wait for A/D conversion/conversions to complete using one of the following options:
   a) Poll for the GO/$\overline{\text{DONE}}$ bit to be cleared if in Single-Shot mode.
   b) Wait for the A/D Interrupt Flag (ADIF) to be set.
   c) Poll for the BFEMT bit to be cleared to signify that at least the first conversion has completed.
6. Read the A/D results, clear the ADIF flag, reconfigure the trigger.

ADDWFC **ADD W and Carry bit to f**

Syntax: [*label*] ADDWFC f [,d [,a]]

Operands: $0 \le f \le 255$
$d \in [0,1]$
$a \in [0,1]$

Operation: (W) + (f) + (C) → dest

Status Affected: N, OV, C, DC, Z

Encoding:

0010	00da	ffff	ffff

Description: Add W, the Carry flag and data memory location, 'f'. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is placed in data memory location, 'f'. If 'a' is '0', the Access Bank will be selected. If 'a' is '1', the BSR will not be overridden.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

Example: ADDWFC REG, W

Before Instruction
Carry bit = 1
REG = 0x02
W = 0x4D
After Instruction
Carry bit = 0
REG = 0x02
W = 0x50

ANDLW **AND Literal with W**

Syntax: [*label*] ANDLW k

Operands: $0 \le k \le 255$

Operation: (W) .AND. k → W

Status Affected: N, Z

Encoding:

0000	1011	kkkk	kkkk

Description: The contents of W are ANDed with the 8-bit literal 'k'. The result is placed in W.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Process Data	Write to W

Example: ANDLW 0x5F

Before Instruction
W = 0xA3
After Instruction
W = 0x03

RETURN **Return from Subroutine**

Syntax: [*label*] RETURN [s]

Operands: s ∈ [0,1]

Operation: (TOS) → PC;
if s = 1:
(WS) → W,
(STATUSS) → STATUS,
(BSRS) → BSR,
PCLATU, PCLATH are unchanged

Status Affected: None

Encoding:

0000	0000	0001	001s

Description: Return from subroutine. The stack is popped and the top of the stack (TOS) is loaded into the program counter. If 's'= 1, the contents of the shadow registers, WS, STATUSS and BSRS, are loaded into their corresponding registers, W, STATUS and BSR. If 's' = 0, no update of these registers occurs.

Words: 1

Cycles: 2

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	No operation	Process Data	POP PC from stack
No operation	No operation	No operation	No operation

Example: RETURN

After Interrupt
PC = TOS

RLCF **Rotate Left f through Carry**

Syntax: [*label*] RLCF f [,d [,a]]

Operands: 0 ≤ f ≤ 255
d ∈ [0,1]
a ∈ [0,1]

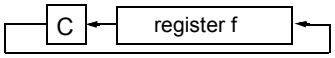
Operation: (f<n>) → dest<n + 1>,
(f<7>) → C,
(C) → dest<0>

Status Affected: C, N, Z

Encoding:

0011	01da	ffff	ffff

Description: The contents of register, 'f', are rotated one bit to the left through the Carry flag. If 'd' is '0', the result is placed in W. If 'd' is '1', the result is stored back in register, 'f'. If 'a' is '0', the Access Bank will be selected, overriding the BSR value. If 'a' = 1, then the bank will be selected as per the BSR value.



Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

Example: RLCF REG, W

Before Instruction
REG = 1110 0110
C = 0

After Instruction
REG = 1110 0110
W = 1100 1100
C = 1

TABLE 26-20: A/D CONVERTER CHARACTERISTICS

PIC18LF2331/2431/4331/4431 (Industrial)			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial				
PIC18F2331/2431/4331/4431 (Industrial)			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
Device Supply							
	AVDD	Analog VDD Supply	VDD – 0.3	—	VDD + 0.3	V	
	AVSS	Analog VSS Supply	VSS – 0.3	—	VSS + 0.3	V	
	IAD	Module Current (during conversion)	— —	500 250	— —	μA μA	VDD = 5V VDD = 2.5V
	IADO	Module Current Off	—	—	1.0	μA	
AC Timing Parameters							
A10	FTHR	Throughput Rate	— —	— —	200 75	ksps ksps	VDD = 5V, single channel VDD < 3V, single channel
A11	TAD	A/D Clock Period	385 1000	— —	20,000 20,000	ns ns	VDD = 5V VDD = 3V
A12	TRC	A/D Internal RC Oscillator Period	— — —	500 750 10000	1500 2250 20000	ns ns ns	PIC18F parts PIC18LF parts AVDD < 3.0V
A13	TCNV	Conversion Time(1)	12	12	12	TAD	
A14	TACQ	Acquisition Time(2)	2(2)	—	—	TAD	
A16	TTC	Conversion Start from External	1/4 TCY	—	—		
Reference Inputs							
A20	VREF	Reference Voltage for 10-Bit Resolution (VREF+ – VREF-)	1.5 1.8	— —	AVDD – AVSS AVDD – AVSS	V V	VDD ≥ 3V VDD < 3V
A21	VREFH	Reference Voltage High (AVDD or VREF+)	1.5V	—	AVDD	V	VDD ≥ 3V
A22	VREFL	Reference Voltage Low (AVSS or VREF-)	AVSS	—	VREFH – 1.5V	V	
A23	IREF	Reference Current	— —	150 μA 75 μA	— —		VDD = 5V VDD = 2.5V
Analog Input Characteristics							
A26	VAIN	Input Voltage(3)	AVSS – 0.3	—	AVDD + 0.3	V	
A30	ZAIN	Recommended Impedance of Analog Voltage Source	—	—	2.5	kΩ	
A31	ZCHIN	Analog Channel Input Impedance	—	—	10.0	kΩ	VDD = 3.0V
DC Performance							
A41	NR	Resolution	10 bits			—	
A42	EIL	Integral Nonlinearity	—	—	<±1	LSb	VDD ≥ 3.0V VREFH ≥ 3.0V
A43	EIL	Differential Nonlinearity	—	—	<±1	LSb	VDD ≥ 3.0V VREFH ≥ 3.0V
A45	EOFF	Offset Error	—	±0.5	<±1.5	LSb	VDD ≥ 3.0V VREFH ≥ 3.0V
A46	EGA	Gain Error	—	±0.5	<±1.5	LSb	VDD ≥ 3.0V VREFH ≥ 3.0V
A47	—	Monotonicity(4)	guaranteed			—	VDD ≥ 3.0V VREFH ≥ 3.0V

Note 1: Conversion time does not include acquisition time. See **Section 21.0 "10-Bit High-Speed Analog-to-Digital Converter (A/D) Module"** for a full discussion of acquisition time requirements.

2: In Sequential modes, TACQ should be 12 TAD or greater.

3: For VDD < 2.7V and temperature below 0°C, VAIN should be limited to range < VDD/2.

4: The A/D conversion result never decreases with an increase in the input voltage and has no missing codes.

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